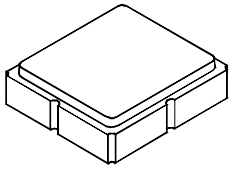
RFMi
A BRAND OF AKOUSTIS

RoHS compliant

SF2251E

1600 MHz SAW Filter

- ***Low-loss RF SAW Filter***
- ***3.0 x 3.0 x 1.4 mm Surface-mount Case***
- ***No Matching Required for 50Ω Operation***
- ***Moisture Sensitivity Level: 1***



SM3030-6

Absolute Maximum Ratings

Rating	Value	Units
Incident Power in Passband	+10	dBm
DC Voltage on any Non-ground Terminal	3	VDC
Operating Temperature Range	-55 to +85	°C
Storage Temperature Range in Tape and Reel	-55 to +95	°C
Maximum Soldering Profile, 5 cycles/10 seconds maximum	260	°C

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			1600		MHz
Insertion Loss, 1580 to 1620 MHz	IL			3.15	5.00	dB
1500 MHz Attenuation Referenced to 0 dB			45	64		dB
1700 MHz Attenuation Referenced to 0 dB			40	47		dB
Terminating Source Impedance	Z_S			50		Ω
Terminating Load Impedance	Z_L			50		Ω

Input/Output Impedance Match	No matching network required for 50 ohm source/load
Case Style	SM3030-6
Lid Symbolization: Y = year, WW = week, S = shift)	992, YWWS

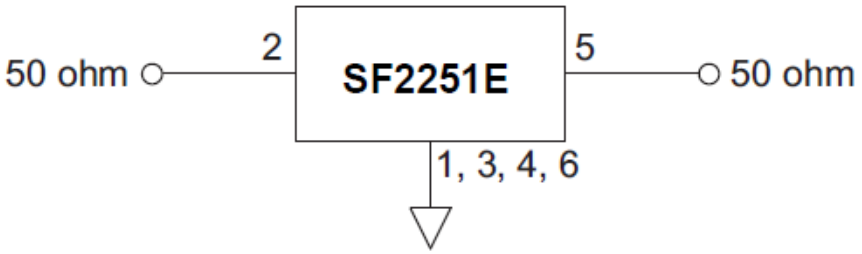
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

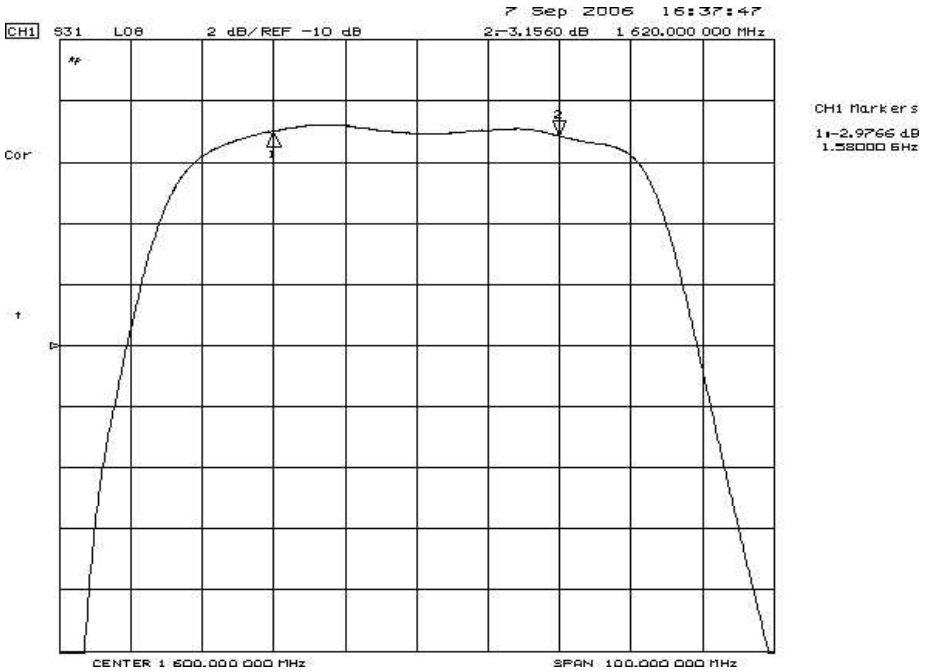
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

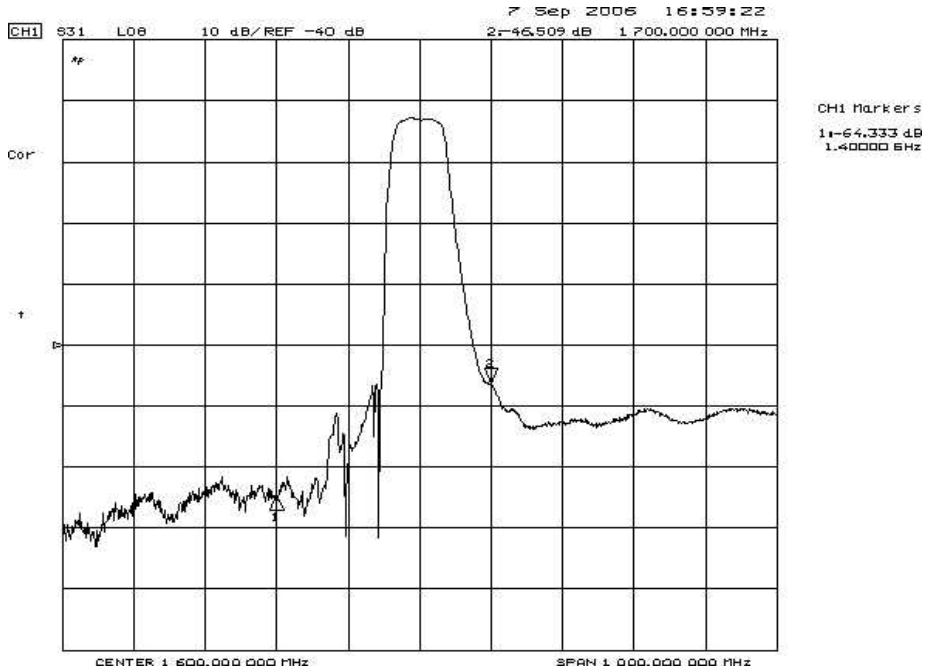
Copyright © 2015 by RFM Integrated Device, Inc.

Matching Circuit



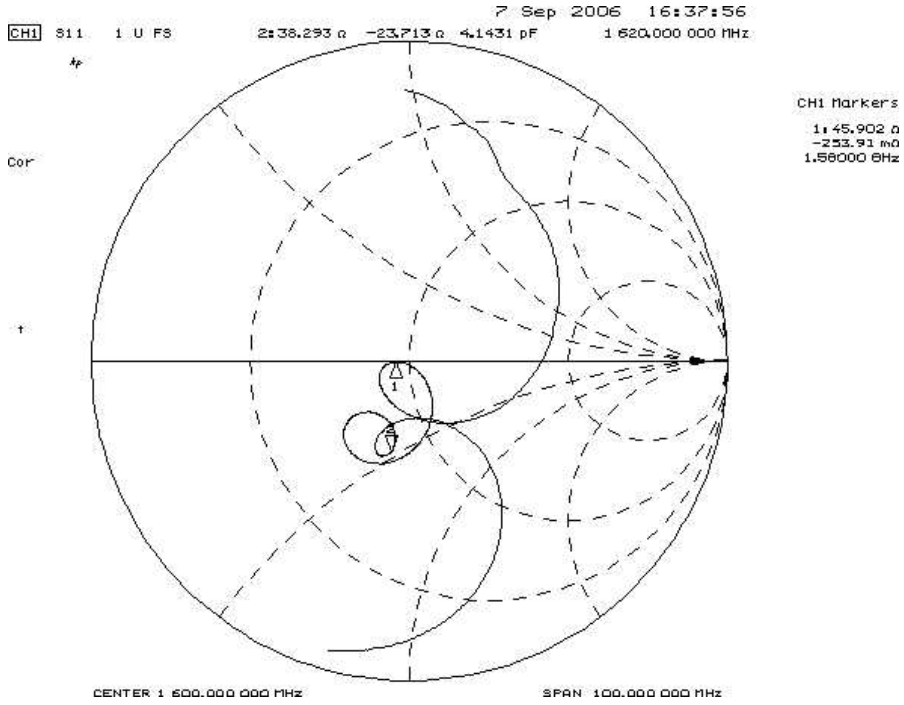
Frequency Response Plots

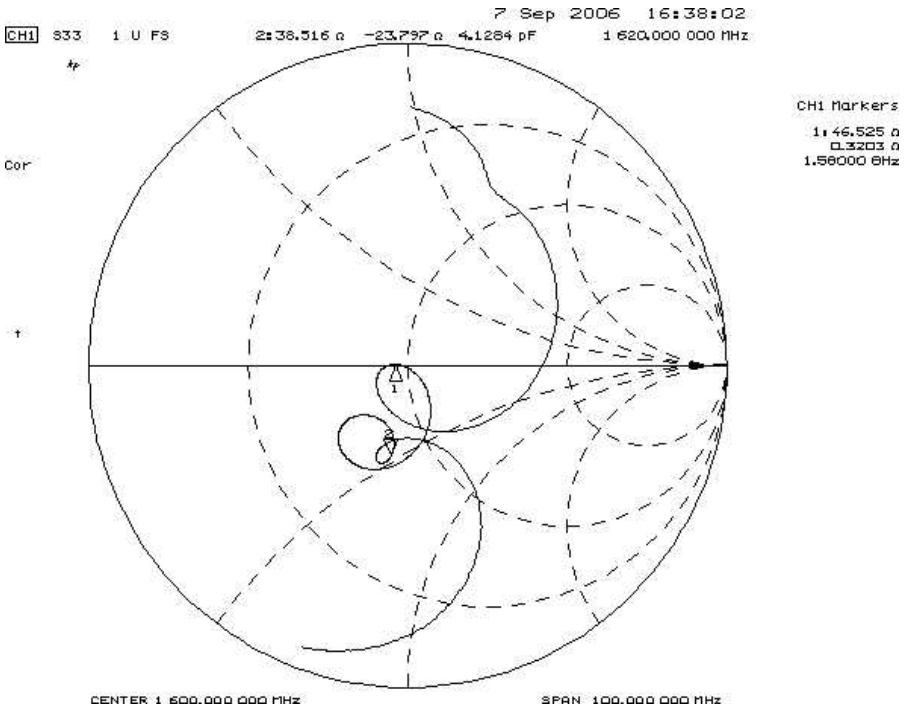




Copyright © 2015 by RFM Integrated Device, Inc.

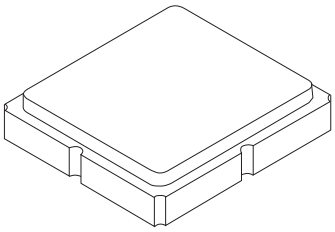
Input/Output Impedance Plots

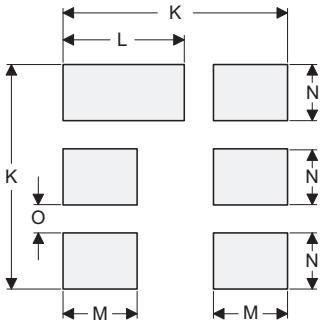




Copyright © 2015 by RFM Integrated Device, Inc.

6-Terminal Ceramic Surface-Mount Case
3.0 X 3.0 mm Nominal Footprint





PCB Footprint Top View

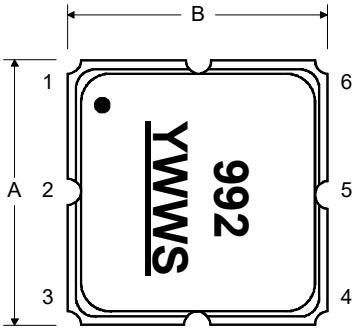
Case and PCB Footprint Dimensions

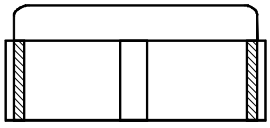
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

Case Materials

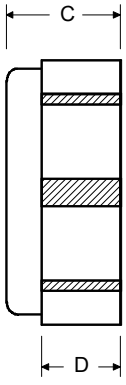
Materials	
Solder Pad Plating	0.3 to 1.0 µm Gold over 1.27 to 8.89 µm Nickel
Lid Plating	2.0 to 3.0 µm Nickel
Body	Al_2O_3 Ceramic

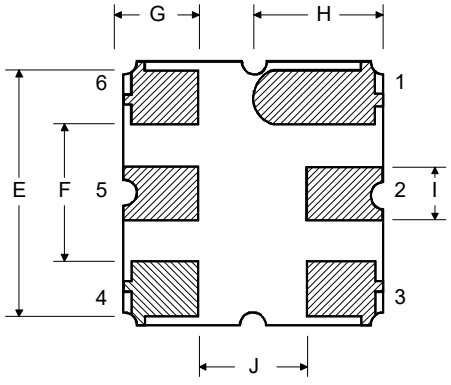
TOP VIEW





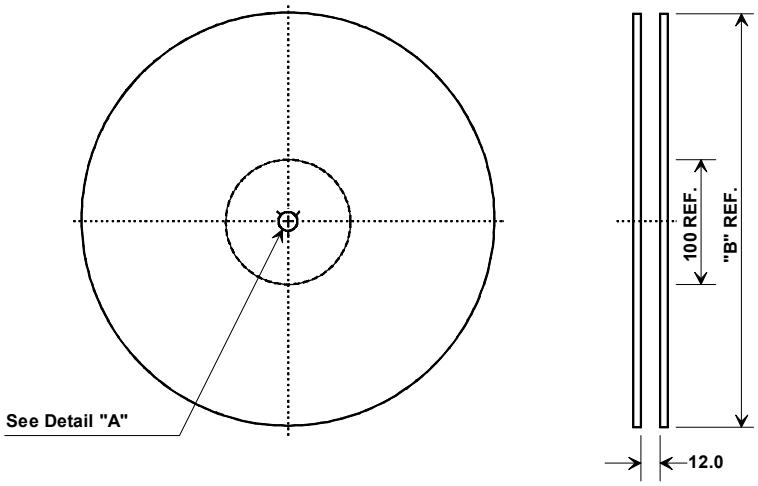
BOTTOM VIEW





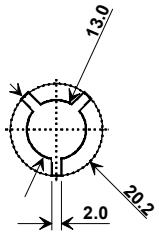
Copyright © 2015 by RFM Integrated Device, Inc.

Tape and Reel Specifications



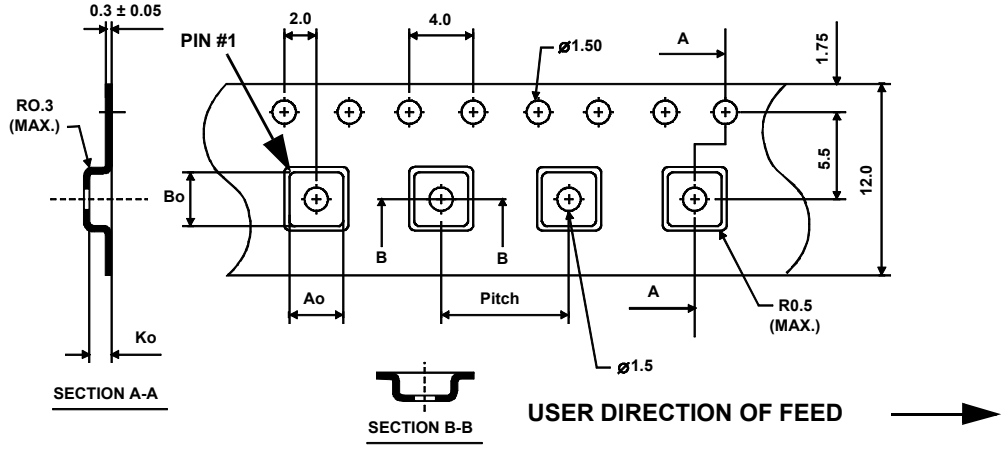
Tape and Reel Standard per ANSI/EIA-481

"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000



COMPONENT ORIENTATION and DIMENSIONS

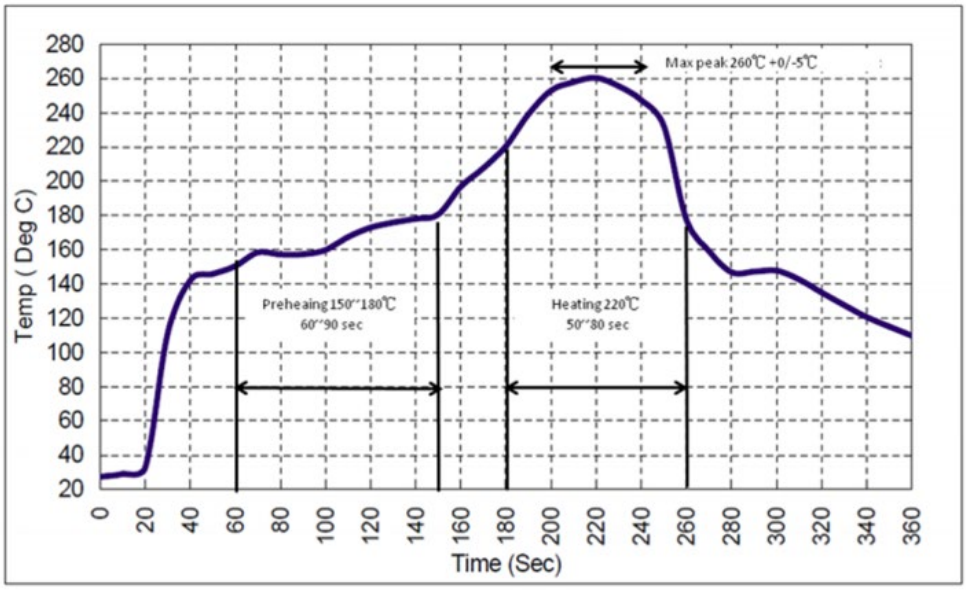
Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm



Copyright © 2015 by RFM Integrated Device, Inc.

Recommended Reflow Profile

1. Preheating shall be fixed at 150~180ºC for 60~90 seconds.
2. Ascending time to preheating temperature 150ºC shall be 30 seconds min.
3. Heating shall be fixed at 220ºC for 50~80 seconds and at 260ºC +0/-5ºC peak (10 seconds).
4. Time: 5 times maximum.



Copyright © 2015 by RFM Integrated Device, Inc.